10-17-2008 10/01/2008 U.S. DEPARTMENT OF COMMERCE FORM PTO-1595 REC o2005 Staas & Halsey LLP 103530132 To the Director of the U.S. Patent and Trademark Office: Fie 1. Name of conveying party(ies): (1) Young-Ki LEE (2) Seog-Moon CHOI (3) Hyung-Jin JEON (4) Sang-Hyun SHIN 2. Name and Address of receiving party(ies): SAMSUNG ELECTRO-MECHANICS CO., LTD. 314, Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-Do, KOREA 443-743 3. Nature of conveyance: Assignment Х Merger Security Agreement Change of Name Other: Execution Date(s): (1), (2), (3), (4), August 18, 2008 4. Application number(s) or patent number(s): This document is being filed together with a new application. This document is being filed after filing of the application: Patent Application No(s)., filed; or (a) Patent No(s)., issued. (b) 5. Name and address of party to whom correspondence concerning document should be mailed: STAAS & HALSEY LLP Our Docket: 1937,1301 Attention: David M. Pitcher 1201 New York Ave., N.W., Suite 700 Washington, D.C. 20005 6. Total number of applications and patents involved: \_\_1 7. Total fee (37 CFR 3.41)......(\$ 40.00 per Patent or Application in Assignment) Enclosed Authorized to be charged to deposit account. 8. Deposit Account No.: 19-3935 (Any underpayment is authorized to be charged to this Deposit Account) (Attach duplicate copy of this page if paying by deposit account) David M. Pitcher, Reg. No. 25,908 October 1, 2008 Name of Person Signing Total number of pages including cover sheet: 2 DO NOT USE THIS SPACE

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PATENT REEL: 021702 FRAME: 0288

U.S. PTO 12/285324 10/01/2008

## U.S. ASSIGNMENT

Docket No.					
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IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

(Insert Name(s) & Address(es) of ASSIGNEE(S))

METHOD THEREOF

SAMSUNG ELECTRO-MECHANICS CO., LTD. 314, Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-Do, KOREA 443-743

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled (Title of Invention)

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and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigne (Typed Name & Signature of Inventor(s)		er/their signature(s). (Typed Name & Signature of Witness(es
1) Young-Ki LEE	August 18.2008	· · · · · · · · · · · · · · · · · · ·
Seog-Moon CHOI	Aug. 18, 2008	
Hyung Jin JEON Hyung-Jin JEON	August 18.2008	
Sang-Hyun SHIN	Argust. 18. 2008	

Additional inventors are being named on separately numbered sheets attached hereto.

PATENT REEL: 021702 FRAME: 0289

**RECORDED: 10/01/2008**